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(54) **SYSTEM AND METHOD FOR THERMAL MANAGEMENT OF STORAGE DEVICES**
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(57) **ABSTRACT**
Methods, systems, and devices for providing computer implemented services are disclosed. To provide the computer implemented services, a data processing system may include hardware components that provide the computer implemented services. Any of the hardware components may have thermal limitations. To mitigate the impact of the thermal limitations, the data processing system may include host circuit card integrated heating assemblies. The heating assemblies may be used to warm hardware components of devices connected to the host circuit card. When connected to the host circuit card, a thermal conduction path between a device and a heating assembly may be established.

